

ABSTRACT OF THE DISCLOSURE

A process for encapsulating an integrated circuit die (403) using a porous carrier (101). In one example, an adhesive structure (e.g. tape) is applied to a porous carrier.

Integrated circuit die is then placed on the adhesive structure. The integrated circuit die is

5 then encapsulated to form an encapsulated structure (505). The carrier is then subjected to a solvent that passes through the carrier to reduce the adhesive strength of the adhesive structure for removal of the carrier from the encapsulated structure.